/ Descriptions

TO-252
Schottky Barrier Diode in a TO-252 Plastic Package.

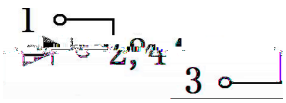
/ Features

High Forward Surge Capability, Ultra Low Forward Voltage Drop, Excellent High Temperature Stability.

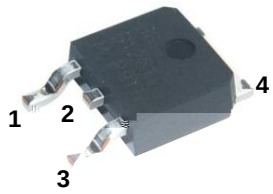
/ Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

/ Equivalent Circuit



/ Pinning



PIN1 Anode PIN 2,4 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

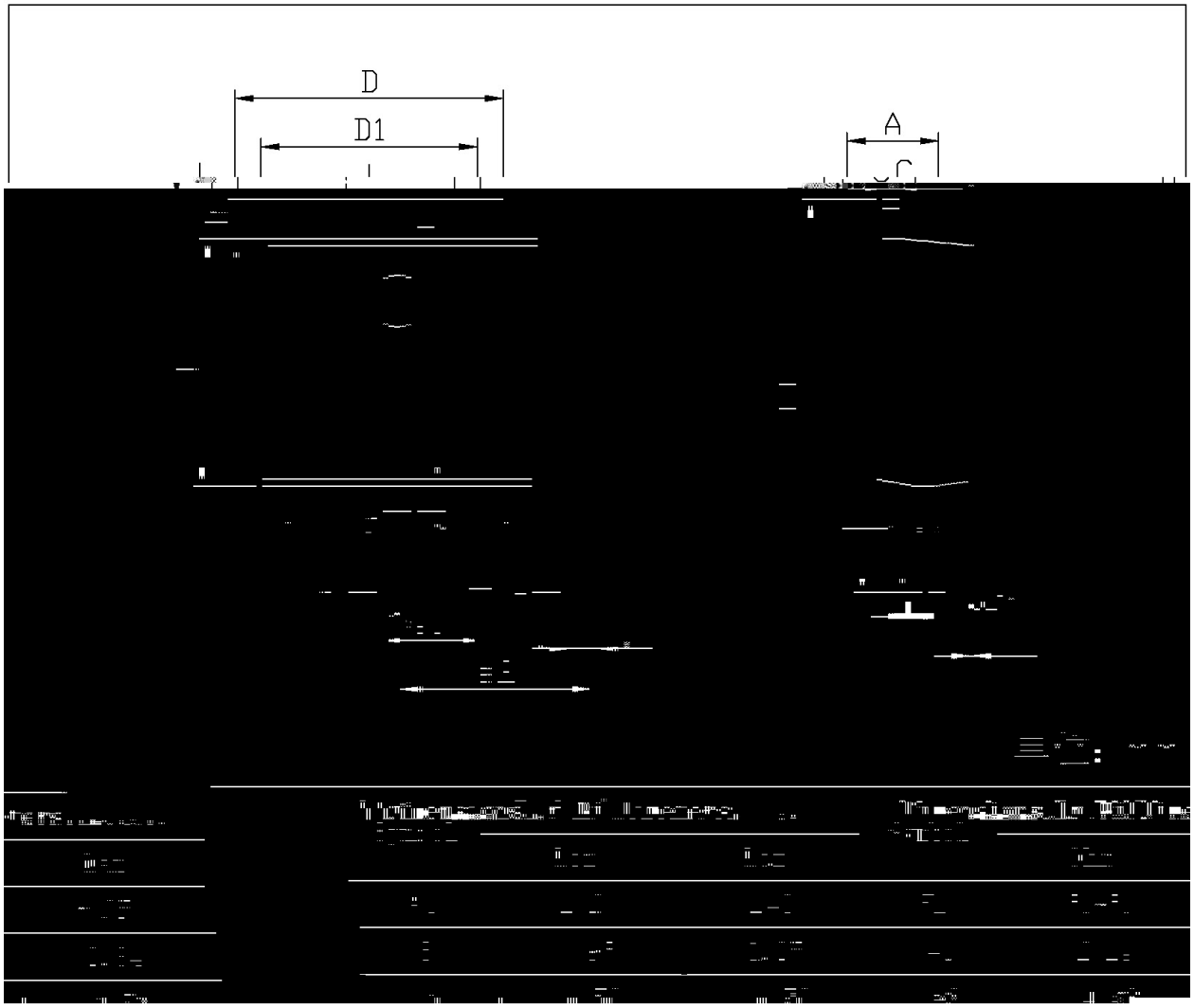
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage Peak Reverse Voltage	V_{RRM} V_{RWM} V_{RM}	200	V
RMS Reverse Voltage	$V_{R(RMS)}$	140	V
Average Rectified Forward Current	$I_{F(AV)}$	10	A
Non Repetitive Peak Surge Current	I_{FSM}	150	A
Junction Temperature Range	$T_{j\ MAX}$	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_{BR}	I_R=0.3mA	200			V
Forward Voltage	V_F	I_F=2A T_J=25		0.68	0.75	V
		I_F=2A T_J=125		0.53	0.58	V
		I_F=10A T_J=25		0.87	0.95	V
		I_F=10A T_J=125		0.70	0.75	V
Instantaneous Reverse Current	I_R Note 1	V_R=200V T_J=25		4	20	uA
		V_R=150V T_J=125		1.9	5	mA
		V_R=200V T_J=125		3.5	10	mA

/Notes

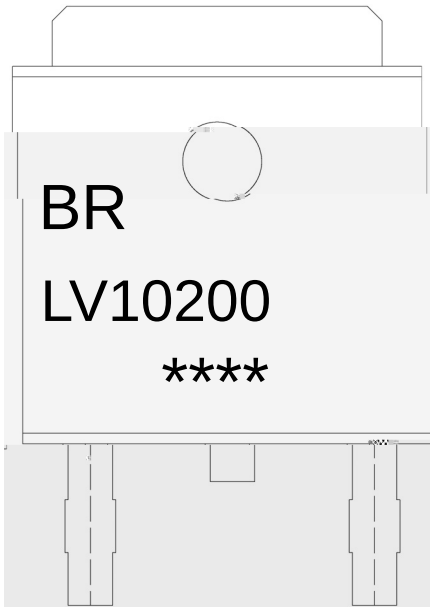
1. /Short duration pulse test used to minimize self-heating effect.

/ Package Dimensions



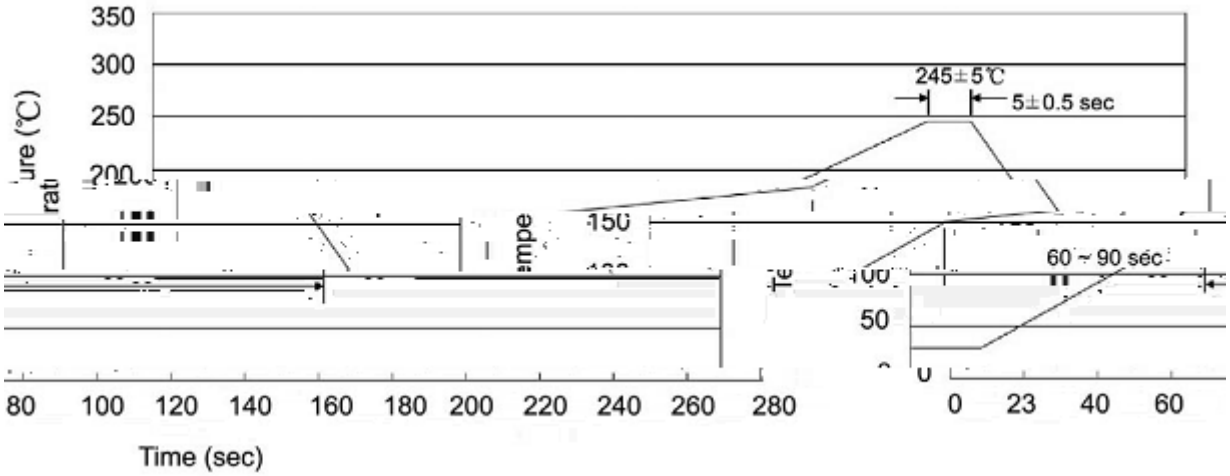


/ Marking Instructions



BR	
10200	
LV	TBR
****	
Note:	
BR:	Company Code
10200	Product Type Code.
LV	TBR Process.
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



										Note:	
1		25	150			60	90sec;			1.Preheating:25~150	, Time:60~90sec.
2		245±5					5±0.5sec;			2.Peak Temp.:245±5	, Duration:5±0.5sec.
3					2	10	/sec.			3. Cooling Speed: 2~10	/sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units				Dimension (unit mm^3)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	